

Amendments to the claims:

This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

Please cancel claim 1.

1-30 (canceled)

31. (New) A method for producing printed wiring boards, comprising the steps of:

forming a first wiring pattern on a surface of a first releasable supporting sheet;

forming a second wiring pattern on a surface of a second releasable supporting sheet;

placing the first releasable supporting sheet on one surface of a first adhesive insulator sheet having holes filled with a first conductive material, and embedding the first wiring pattern in the first adhesive insulator sheet so that the first wiring pattern is connected with the first conductive material;

placing the second releasable supporting sheet on the other surface of the first adhesive insulator sheet, and embedding the second wiring pattern in the first adhesive insulator sheet so that the second wiring pattern is connected with the first conductive material; and

removing the first and second releasable supporting sheets from the first adhesive insulator sheet.

32. (New) The method according to claim 31, comprising the steps of:

forming a third wiring pattern on a surface of a third releasable supporting sheet;

laminating a second adhesive insulator sheet having holes filled with a second conductive material on the first adhesive insulator sheet;

placing the third releasable supporting sheet on a surface of the second adhesive insulator sheet, and embedding the third wiring pattern in the second adhesive insulator sheet so that the third wiring pattern is connected with the second conductive material; and

removing the third releasable supporting sheet from the second adhesive insulator sheet.

33. (New) the method according to claim 31,

wherein the first conductive material is formed of a conductive paste.

34. (New) The method according to claim 31,

wherein first releasable supporting sheet has conductivity and the step of forming the first wiring pattern on the surface of the first releasable supporting sheet is a step of forming the first wiring pattern by plating through a wiring pattern resist formed on the surface of the first releasable supporting sheet.

35. (New) The method according to claim 31,

wherein the step of forming the first wiring pattern on the surface of the first releasable supporting sheet is a step of forming the first wiring pattern by printing a conductive paste on the surface of the first releasable supporting sheet.

36. (New) The method according to claim 31,

wherein the step of forming the first wiring pattern on the surface of the first releasable supporting sheet comprises the steps of;

forming a wiring pattern on the first releasable supporting sheet;

forming an insulator layer on the wiring pattern;

forming via holes at predetermined positions of the insulator layer;

and

forming the first wiring pattern on an upper surface of the insulating layer.

37. (New) The method according to claim 31,

wherein the first adhesive insulator sheet is in a semi-hardened state.

38. (New) The method according to claim 31,

wherein the first adhesive insulator sheet is formed of a porous base material.

39. (New) The material according to claim 31,

wherein the first adhesive insulator sheet is hardened by application of heat and pressure, the first and second releasable supporting sheets are removed from the first adhesive insulator sheet after hardening.

40. (New) The method according to claim 31,

wherein the adhesive insulator sheet is formed of a polyester or polyimide sheet coated with an adhesive or glue, or a glass-epoxy prepreg.

41. (New) The method according to claim 31,

wherein the step of removing the releasable supporting sheets comprises removing the releasable supporting sheets by peeling or etching.